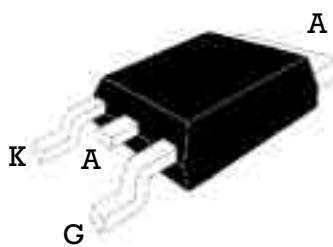


**SURFACE MOUNT SCR**

<b>DPAK (Plastic)</b> 	<b>On-State Current</b> 8 Amp	<b>Gate Trigger Current</b> < 200 $\mu$ A
	<b>Off-State Voltage</b> 200 V ÷ 600 V	
<p>These series of <b>Silicon Controlled Rectifier</b> use a high performance PNPN technology.</p> <p>These parts are intended for general purpose applications where high gate sensitivity is required using surface mount technology.</p>		

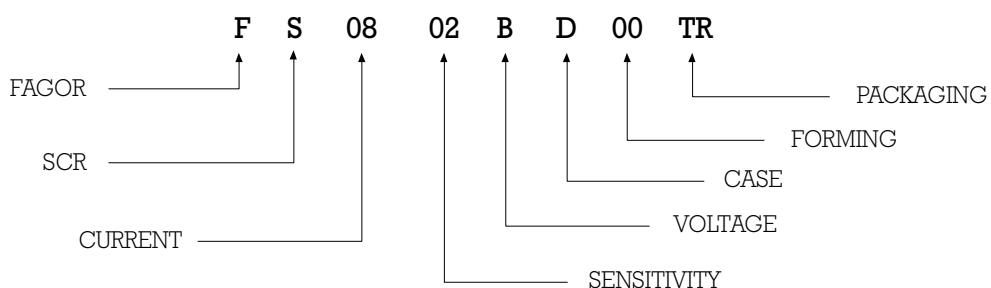
**Absolute Maximum Ratings, according to IEC publication No. 134**

SYMBOL	PARAMETER	CONDITIONS	Min.	Max.	Unit
$I_{T(RMS)}$	On-state Current	180° Conduction Angle, $T_c = 110^\circ C$		8	A
$I_{T(AV)}$	Average On-state Current	Half Cycle, $\alpha = 180^\circ$ , $T_c = 110^\circ C$		5	A
$I_{TSM}$	Non-repetitive On-State Current	Half Cycle, 60 Hz		73	A
$I_{TSM}$	Non-repetitive On-State Current	Half Cycle, 50 Hz		70	A
$I^{2t}$	Fusing Current	$t_p = 10ms$ , Half Cycle		24	$A^2s$
$V_{GRM}$	Peak Reverse Gate Voltage	$I_{GR} = 10 \mu A$		8	V
$I_{GM}$	Peak Gate Current	20 $\mu s$ max.		4	A
$P_{GM}$	Peak Gate Dissipation	20 $\mu s$ max.		5	W
$P_{G(AV)}$	Gate Dissipation	20ms max.		1	W
$T_j$	Operating Temperature		-40	+125	$^\circ C$
$T_{stg}$	Storage Temperature		-40	+150	$^\circ C$
$T_{sld}$	Soldering Temperature	10s max.		260	$^\circ C$

SYMBOL	PARAMETER	CONDITIONS	VOLTAGE			Unit
			B	D	M	
$V_{DRM}$ $V_{RRM}$	Repetitive Peak Off State Voltage	$R_{GK} = 1 K$	200	400	600	V

**SURFACE MOUNT SCR****Electrical Characteristics**

SYMBOL	PARAMETER	CONDITIONS		SENSITIVITY	Unit
		MIN	MAX		
$I_{GT}$	Gate Trigger Current	$V_D = 12 \text{ V}_{DC}, R_L = 140 \Omega, T_j = 25^\circ\text{C}$	MIN MAX	200 1 5	$\mu\text{A}$ $\text{mA}$ $\mu\text{A}$
$I_{DRM} / I_{RRM}$	Off-State Leakage Current	$V_D = V_{DRM}, R_{GK} = 220 \Omega, T_j = 125^\circ\text{C}$ $V_R = V_{RRM}, T_j = 25^\circ\text{C}$	MAX MAX	1.6 0.8	$\text{V}$ $\text{V}$
$V_{TM}$	On-state Voltage	at $I_T = 16 \text{ Amp}, t_p = 380 \mu\text{s}, T_j = 25^\circ\text{C}$	MAX	0.1	$\text{V}$
$V_{GT}$	Gate Trigger Voltage	$V_D = 12 \text{ V}_{DC}, R_L = 140 \Omega, T_j = 25^\circ\text{C}$	MAX	0.1	$\text{V}$
$V_{GD}$	Gate Non Trigger Voltage	$V_D = V_{DRM}, R_L = 3.3\text{K}, R_{GK} = 220 \Omega, T_j = 125^\circ\text{C}$	MIN	5	$\text{mA}$
$I_H$	Holding Current	$I_T = 50 \text{ mA}, R_{GK} = 1\text{K}, T_j = 25^\circ\text{C}$	MAX	6	$\text{mA}$
$I_L$	Latching Current	$I_G = 1 \text{ mA}, R_{GK} = 1 \text{ K}$	MAX	50	$\text{A}/\mu\text{s}$
$dv/dt$	Critical Rate of Voltage Rise	$V_D = 0.67 \times V_{DRM}, R_{GK} = 220 \Omega, T_j = 125^\circ\text{C}$	MIN	20	$^\circ\text{C}/\text{W}$
$di/dt$	Critical Rate of Current Rise	$I_G = 2 \times I_{GT}, t_r = 100 \text{ ns}, F = 60 \text{ Hz}, T_j = 125^\circ\text{C}$	MIN	70	$^\circ\text{C}/\text{W}$
$R_{th(j-c)}$	Thermal Resistance Junction-Case for DC			0.85	$\text{V}$
$R_{th(j-a)}$	Thermal Resistance Junction-Amb for DC			46	$\text{m}$
$V_{t0}$	Threshold Voltage	$T_j = 125^\circ\text{C}$	MAX		
$R_d$	Dynamic resistance	$T_j = 125^\circ\text{C}$	MAX		





## SURFACE MOUNT SCR

Fig. 1: Maximum average power dissipation versus average on-state current.

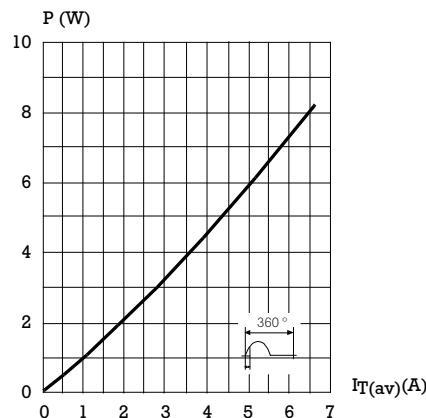


Fig. 3: Relative variation of thermal impedance junction to case versus pulse duration.

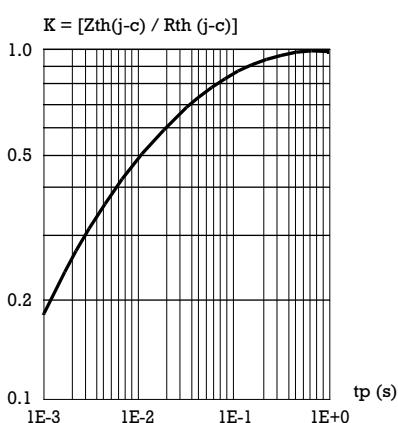


Fig. 5: Non repetitive surge peak on-state current versus number of cycles.

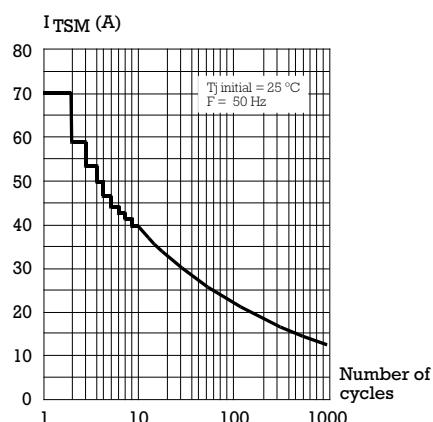


Fig. 2: Average and D.C. on-state current versus case temperature.

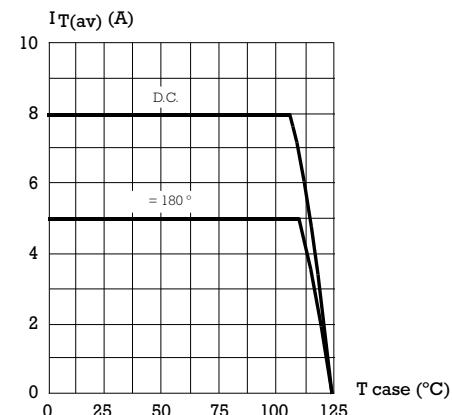


Fig. 4: Relative variation of gate trigger current, holding and latching current versus junction temperature.

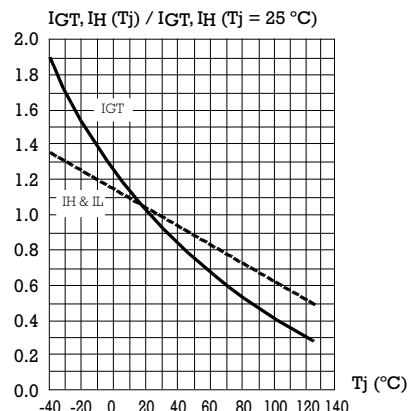
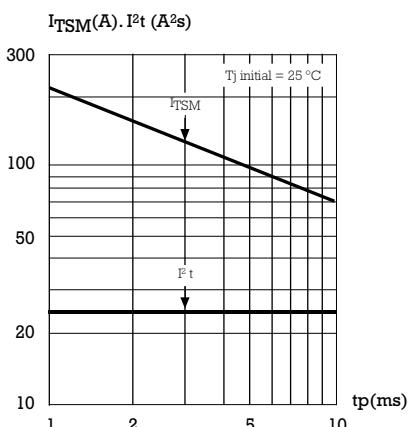


Fig. 6: Non repetitive surge peak on-state current for a sinusoidal pulse with width: tp < 10 ms, and corresponding value of I<sup>2</sup>t.



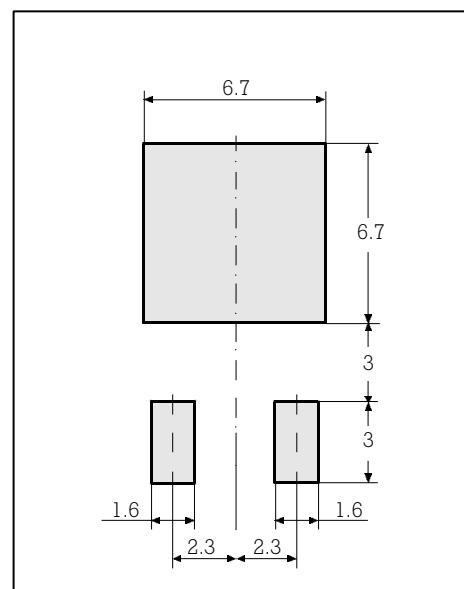
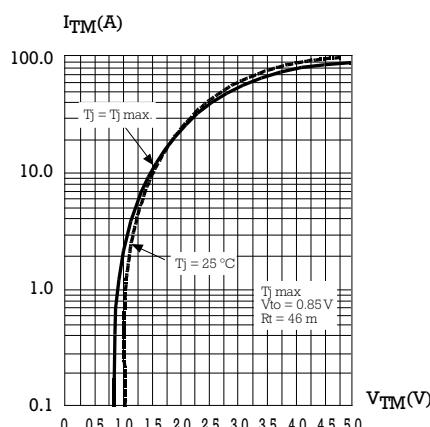
Feb - 03



## SURFACE MOUNT SCR

## FOOT PRINT

Fig. 8: On-state characteristics (maximum values).



## PACKAGE MECHANICAL DATA DPAK TO 252-AA

REF.	DIMENSIONS		
	Milimeters		
	Min.	Nominal	Max.
A	2.18	2.3±0.18	2.39
A1	0	0.12	0.127
b	0.64	0.75±0.1	0.89
c	0.46		0.61
c1	0.46		0.56
c2		0.8±0.013	
D	5.97	6.1±0.1	6.22
D1	5.21		5.52
E	6.35	6.58±0.14	6.73
E1	5.20	5.36±0.1	5.46
e		2.28BSC	
H	9.40	9.90±0.15	10.41
L	1.40		1.78
L1	2.55	2.6±0.05	2.74
L2	0.46	0.5±0.013	0.58
L3	0.89	1.20±0.05	1.27
L4	0.64	0.83±0.1	1.02

Marking: type number  
Weight: 0.2 g